

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC6132xxxxER-G  
Typical Mass:         6       mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.235	Silicon	39100	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	1.100	Nickel	183400	7440-02-0
	0.087	Silver	14600	7440-22-4
	0.016	Gold	2700	7440-57-5
Die attach	0.020	Epoxy Resin	3300	—
	0.016	Silica	2700	60676-86-0
Bonding wire	0.045	Gold	7600	7440-57-5
Resin	4.032	Silica	672000	60676-86-0
	0.246	Epoxy Resin	41100	—
	0.202	Phenol Resin	33600	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."